



Material Content Data Sheet



Sales Product Name		TLF50211EL		Issued		28. August 2013		
MA#		MA001056014						
Package		PG-SSOP-14-3		Weight*		82.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.797	2.17	2.17	21671	21671
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8307	
wire	non noble metal	copper	7440-50-8	27.978	33.73	34.61	337304	346130
	noble metal	gold	7440-57-5	0.130	0.16	0.16	1564	1564
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1203
plastics	plastics	epoxy resin	-	4.592	5.54		55358	
	inorganic material	silicondioxide	60676-86-0	45.218	54.50	60.16	545159	601720
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11768	11768
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9254	9254
glue	plastics	epoxy resin	-	0.164	0.20		1973	
	noble metal	silver	7440-22-4	0.491	0.59	0.79	5920	7893
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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